B2558 BOARD SPECIFICATIONS

1. Board Layers: 4

2. Layer Stack Order:
   - Layer1 (Artwork_1): Top component layer (Signal_1), 1 oz, Z=50 ohm
   - Layer2 (Artwork_2): Power_1 (VCC), 1 oz
   - Layer3 (Artwork_3): Power_2 (GROUND), 1 oz
   - Layer4 (Artwork_4): Bottom component layer (signal_2), 1 oz, Z=50 ohm

3. Apply silkscreen on both side:
   - Artwork_5: Top silkscreen
   - Artwork_6: Bottom silkscreen

4. Apply solder mask over bare copper on both side:
   - Artwork_7: Top solder mask
   - Artwork_8: Bottom solder mask

5. Material: FR4

6. Board thickness: 0.062'' +/- 0.010

7. Send me layer thickness specification for impedance verification

8. Copper thickness 1 oz before plating for all layers

9. Ni/Au plating (3 to 8 micro-inches soft gold) over bare copper

10. Trace width/gap=5/5 mils

11. All 5 mil trace impedance are controlled at 50 ohm +/-10%

12. All dimensions are in inches unless otherwise noted.

BOARD's DRILL SCHEDULE

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Contact person:
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SCH# B2557
SREC B2558
ASME B2559